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Date:	2/2/2014
P/N:	PCB000895
Layers:	4
Total Thickness:	1.6mm±10%
Finish:	Immersion silver

Stack-up and impedance requirements

Material:	FR4-High TG
PCB size and PCB units per array	127.0mm X 25.0; Four units per
PCB Utilization (%)	
Gold finger:	No
Back drill depth/width types on CS:	0
Back drill depth/width types on PS:	0



All dimensions are in mils unless otherwise stated

Impedance parameters															
Differential pairs parameters								SE signal parameters							
Default		Neck-down		Imp.[Ω]	Default Width	Neck-down Width									
Width	Space	Width	Space												
Imp. [Ω]															

Copper parameters				Resin parameters				
Layer	signal/ Power/ GND	Copper weight [oz]	Copper thickness after plaiting [Mil]	Copper roughness	Dielectric thickness	Material	Glass type	Resin content [%]
Layer 1 - CS Core	Power	2	3.4					
			20		>4	FR4-HIGH TG	EM827 Core 20mil	
Layer 2 Pre - PEG	Signal	2						
			7.3		>4	FR4-HIGH TG	EM827 PP 1080X3 (7.3mil)	
Layer 3 Core	Power	2						
			20		>4	FR4-HIGH TG	EM827 Core 20mil	
Layer 4 - PS	Signal	2	3.4					
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Notes:

1	The dielectric thickness, line widths and differential space values are nominal values. Minor changes can be done to meet the impedance requirements.(HW designer approval is a must)
2	Trace widths are nominal finished dimensions.